

Client's ref.: TSMC2003-0143
Our ref: 0503-9983-US/final/Lemon

ABSTRACT OF THE DISCLOSURE

A process of dual damascene or damascene. The dual damascene process comprises providing an etching apparatus, a DCM machine and a wafer, the wafer having a metal line, a stop
5 layer, a dielectric layer, a contact, and a photoresist layer. The dielectric layer and the contact are etched in the etching apparatus to form a trench. The photoresist and the contact are ashed in the DCM machine. Finally the wafer is wet cleaned.